

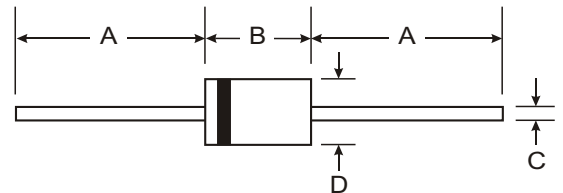
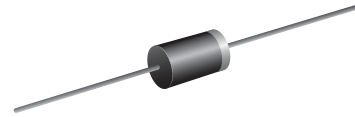
**VOLTAGE RANGE: 600V**  
**CURRENT: 1.0 A**

### Features

- Miniature Size
- Low Forward Voltage drop
- Low Reverse Leakage Current
- High Surge Capability

### Mechanical Data

- Case: DO - 41
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Weight: 0.35 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



DO-41		
Dim	Min	Max
A	25.40	—
B	4.06	5.21
C	0.71	0.864
D	2.00	2.72
All Dimensions in mm		

### Maximum Ratings @ T<sub>A</sub> = 25°C unless otherwise specified

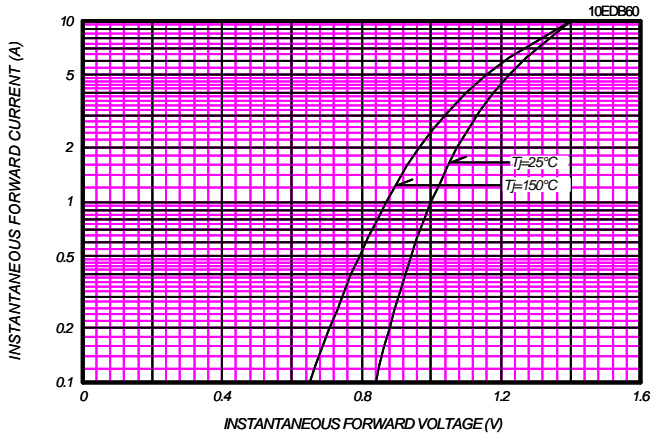
Characteristic	Symbol	10EDB60	Unit
Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	600	V
Average Rectified Output Current 50Hz Half Sine Wave Resistive Load	I <sub>O</sub>	T <sub>a</sub> =39 °C *1 1.0 T <sub>a</sub> =26 °C *2 0.9	A
RMS Forward Current Surge Forward Current 50Hz Half Sine Wave, 1cycle, Non-repetitive	I <sub>F(RMS)</sub>	1.57	A
Surge Forward Current	I <sub>FSM</sub>	45	A
Operating Junction Temperature Range	T <sub>jw</sub>	- 40 to + 150	°C
Storage Temperature Range	T <sub>stg</sub>	- 40 to + 150	°C

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit	
Peak Reverse Current	I <sub>RM</sub>	T <sub>j</sub> = 25 °C, V <sub>RM</sub> = V <sub>RRM</sub>	-	-	10	μA	
Peak Forward Voltage	V <sub>FM</sub>	T <sub>j</sub> = 25 °C, I <sub>FM</sub> = 1.0A	-	-	1.0	V	
Thermal Resistance	R <sub>th(j-a)</sub>	Junction to Ambient	P.C. Board mounted*1	-	-	110	°C/W
			Without Fin *2	-	-	140	

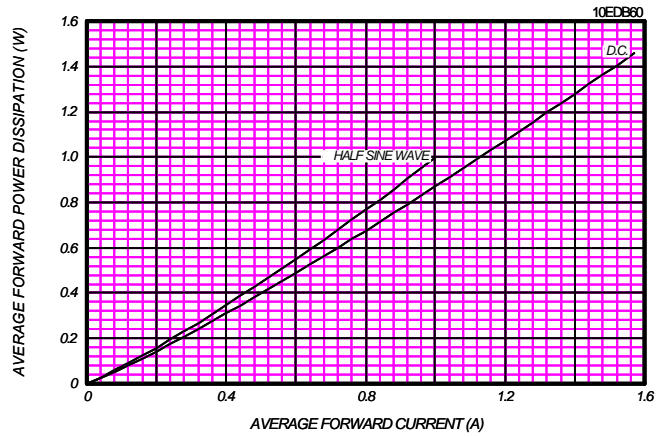
\*1: P.C. Board mounted (L=3mm, Print Land=5 x 5mm, Both Sides)

\*2: Without Fin or P.C. Board mounted

FORWARD CURRENT VS. VOLTAGE

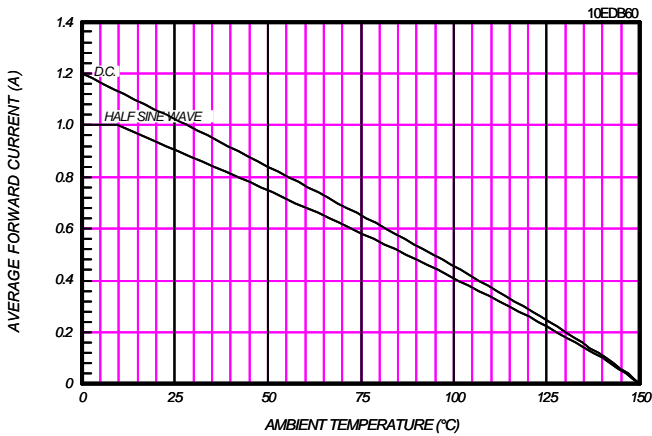


AVERAGE FORWARD POWER DISSIPATION



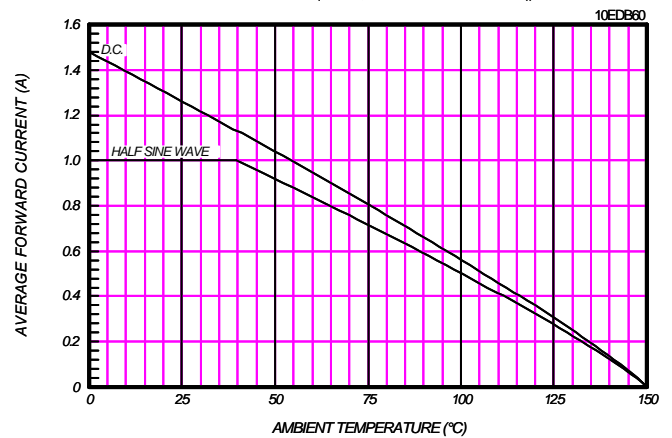
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Without Fin or P.C. Board



AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

P.C. Board mounted (L=3mm, Print Land=5x5mm, Both Sides)



SURGE CURRENT RATINGS

f=50Hz, Half Sine Wave, Non-Repetitive, No Load

